



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Qing Ma Et Al.

§ Group Art Unit:

Serial No.: 10/643,427

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Filed: August 19, 2003

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For: Packaging Microelectro-
mechanical Structures

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Examiner:

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Atty. Dkt. No.:

ITL.0725D1US
(P14251D)

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Applicant submits the references listed on the attached form PTO 1449, copies of which are enclosed. A copy of a communication dated February 3, 2004 from a foreign patent office in a counterpart application is also enclosed. I, the undersigned, hereby certify that each item of information contained in the Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement. Please apply any charges or credits to Deposit Account No. 20-1504 (ITL.0725D1US).

Respectfully submitted,

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February 3, 2004

Date

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Monica Jacobs



INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

ATTY DOCKET NO. ITL.0725D1US (P14251D)	SERIAL NO. 10/643,427
APPLICANT(S): Qing Ma et al.	
FILING DATE: August 19, 2003	GROUP ART UNIT:

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
A.	US 2001/0055836 A1	12/27/2001	Kunda			
B.	6,140,144	10/31/2000	Najafi et al.			
C.						
D.						
E.						
F.						

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
G.	EP 0 994 330 A1	04/19/2000	EPO			
H.						
I.						
J.						
K.						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

L.	Brown et al., <i>Micromachined Micropackaged Filter Banks and Tunable Bandpass Filters</i> , Wireless Communications Conference, 1997, Proceedings Boulder, CO, USA Aug. 11-13, 1997, New York, NY, US, IEEE, USA, Pgs. 193-197.
M.	Mayer et al., <i>Flip-Chip Packaging for Smart MEMS</i> , Smart Structures and Materials, 1998, Smart Electronics and MEMS, San Diego, CA, USA March 2-4, 1998, Proceedings of the SPIE-The Intl. Society for Optical Engineering, 1998, SPIE-INT. Soc. Opt. Eng., USA, Pgs. 183-193.
N.	Markus et al al., <i>Smart MEMS: Flip Chip Integration of MEMS and Electronics</i> , Proceedings of the SPIE, SPIE, Bellingham, VA, USA, Vol. 2448, pgs. 82-92.
O.	Drayton et al., <i>Advanced Monolithic Packaging Concepts for High Performance Circuits and Antennas</i> , 1996 IEEE MTT-S Intl. Microwave Symposium Digest, San Francisco, June 17-21, 1996, IEEE MTT-S Intl. Microwave Symposium Digest, New York, IEEE, USA, Vol. 3, pgs. 1615-1618.
P.	Park et al, <i>Packaging of the RF-MEMS Switch</i> , Design Characterization and Packaging of MEMS and Microelectronics II, Adelaide, SA, Australia, Dec. 17-19, 2001, Proceedings of the SPIE - The Intl. Society for Optical Engineering, 2001, SPIE-Int. Soc. Opt. Eng., USA, Pgs. 234-243.
Q.	
R.	

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.